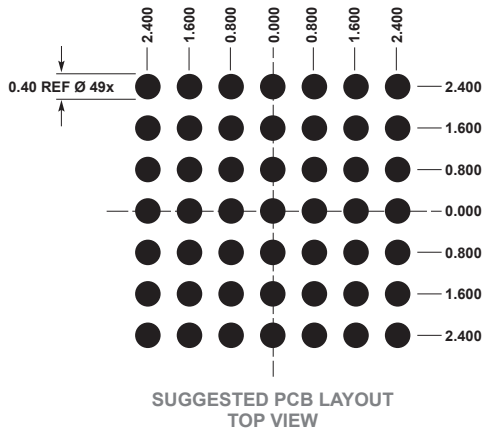
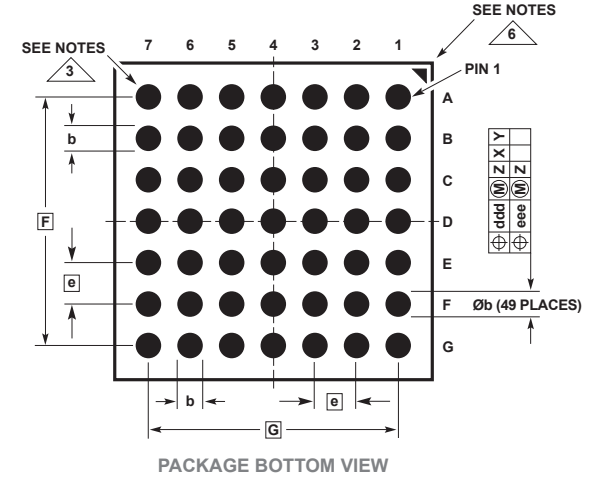
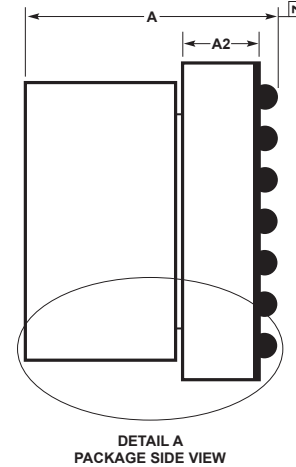
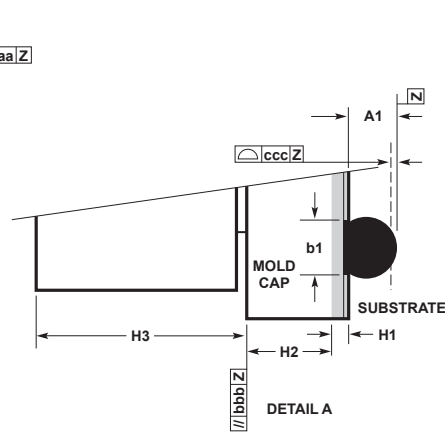
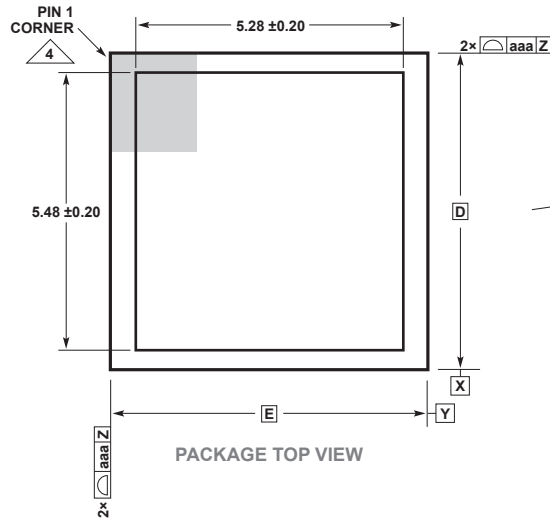


49-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
6.25mm × 6.25mm × 5.07mm
 (Reference DWG # BC-49-9)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.76	5.07	5.39	
A1	0.30	0.40	0.50	BALL HT
A2	1.43	1.52	1.61	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		6.25		
E		6.25		
e		0.80		
F		4.80		
G		4.80		
H1		0.32 REF		SUBSTRATE THK
H2		1.20 REF		MOLD CAP HT
H3			3.28	INDUCTOR HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.20	
eee			0.08	
TOTAL NUMBER OF BALLS: 49				

- NOTES:**
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994**
 - 2. ALL DIMENSIONS ARE IN MILLIMETERS**
 - 3. BALL DESIGNATION PER JEP95**
 - 4. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE**
 - 5. PRIMARY DATUM -Z- IS SEATING PLANE**
 - 6. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY**

